PC/ LED/ IC 自動化設備
解決方案

AllRing Tech
萬潤科技簡介

Presented by Allring

About Us

Establish

May 24. 1996

Chairman

Larry Lu

Capital

833 Million

Business

Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing industries

60%

R&D

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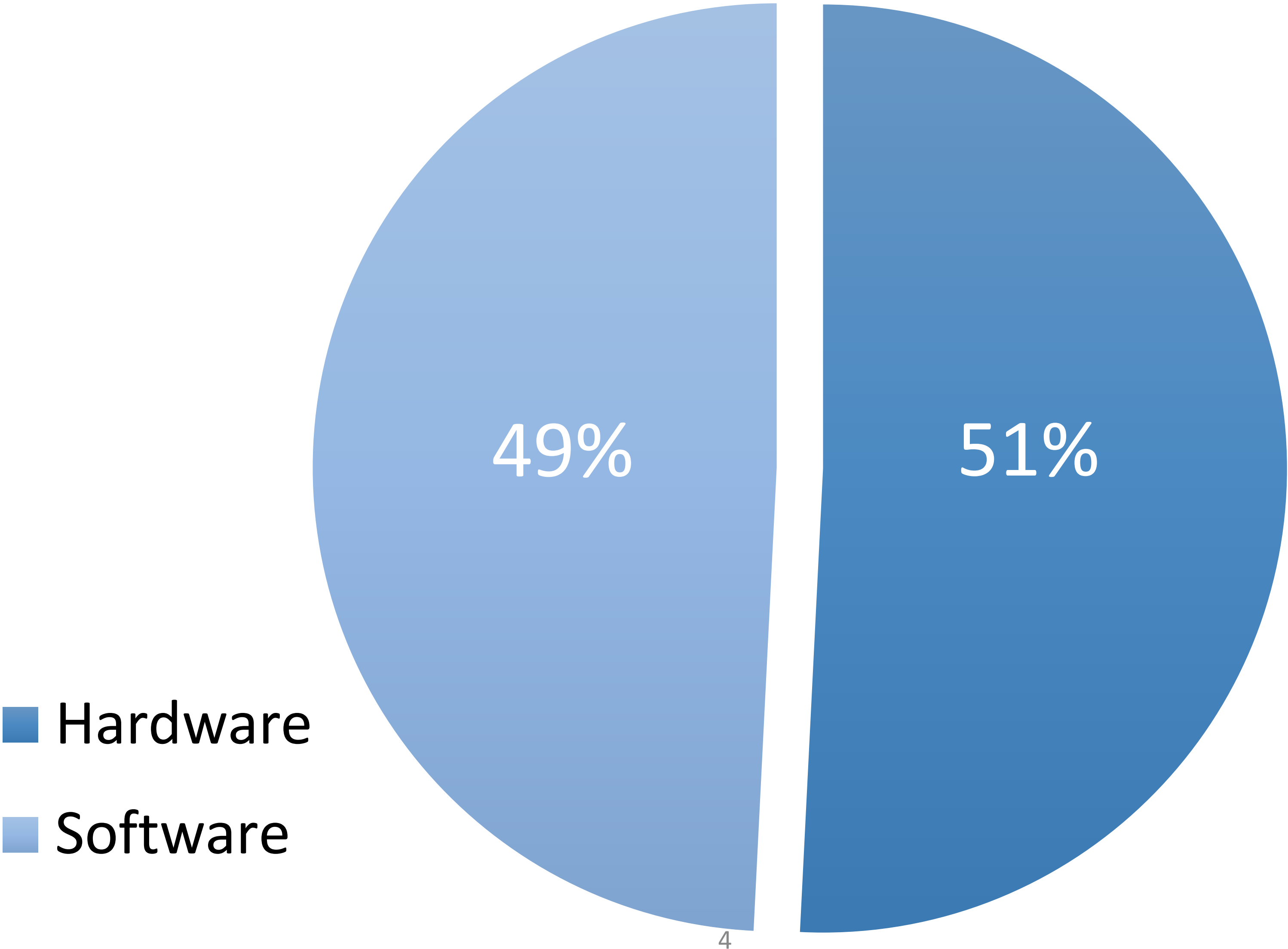
R&D



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Advance Package

Packaging Type		Manufacturer		Application
SIP (system in package)		OSAT	ASE	Smart phone IoT Mobile
			USI	
		Module house	Hon Hai	
			Luxshare	
		Component	AAC	
			AMS	
3D Package	InFO,CoWoS	Foundry	TSMC	Smart Phone IoT Mobile
	SoIC		TSMC	
Flip chip	2D/2.5D	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			Chipbond	
			Powertech	

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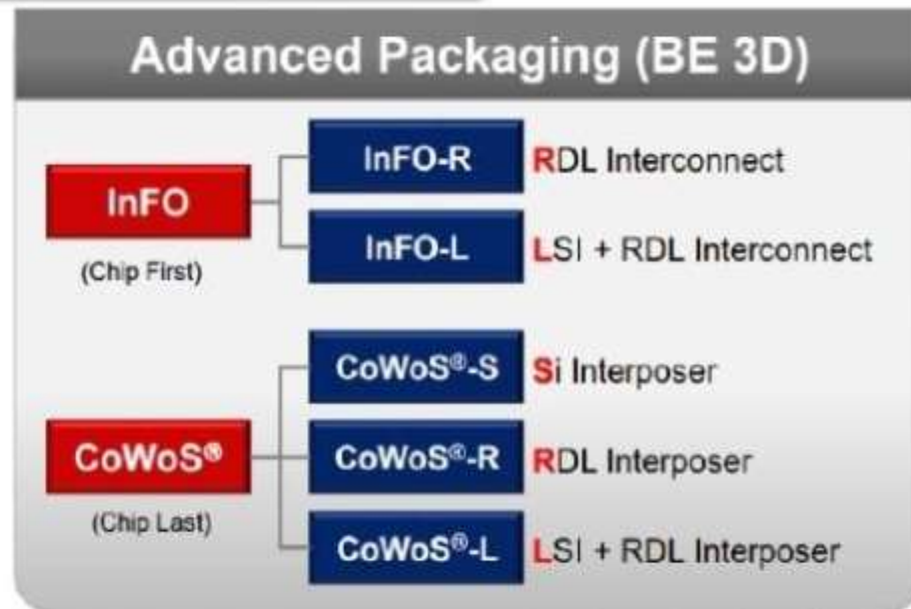
TSMC's 3D Fabric

TSMC 3DFabric™

SoIC: System on Integrated Chips



InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect

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Advance Package

- Advanced packaging process
  - High Performance 2D with SoC & SoIC
    - Flip Chip – MCM(SiP)
    - （Multi-chip module；MCM）
  - 2.5D with SoC
    - COWOS
    - INFO
  - 3D with (SoIC & WoW)
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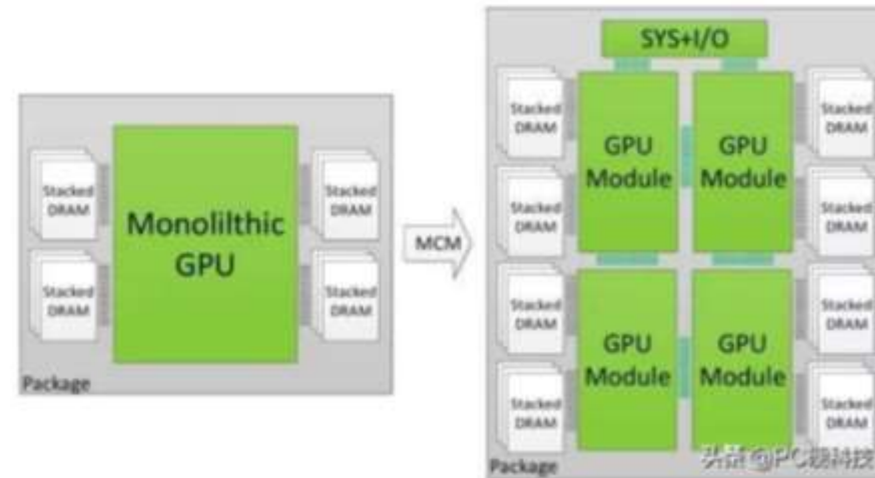
    - INFO



Source: TSMC

PUBLIC

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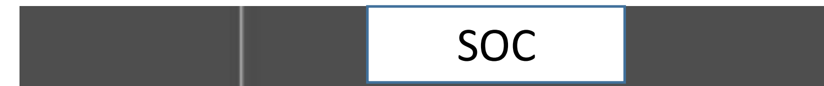

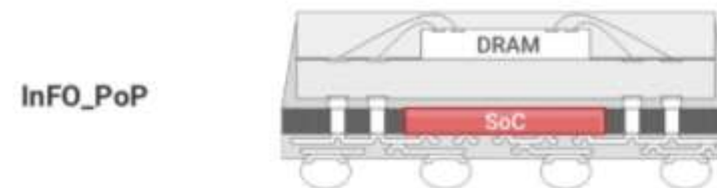

PUBLIC

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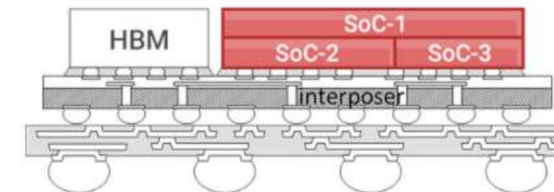

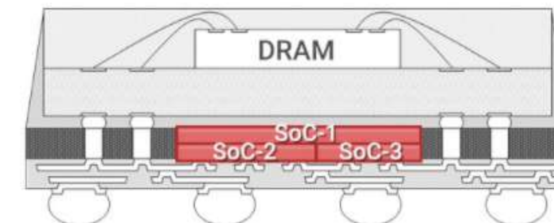

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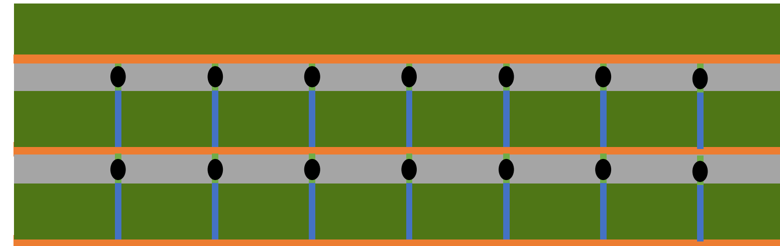

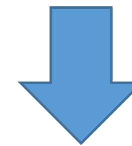

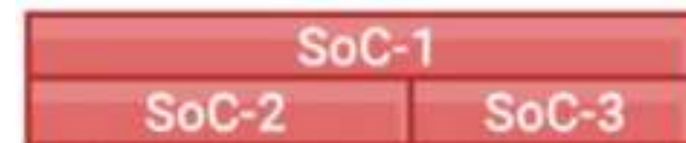

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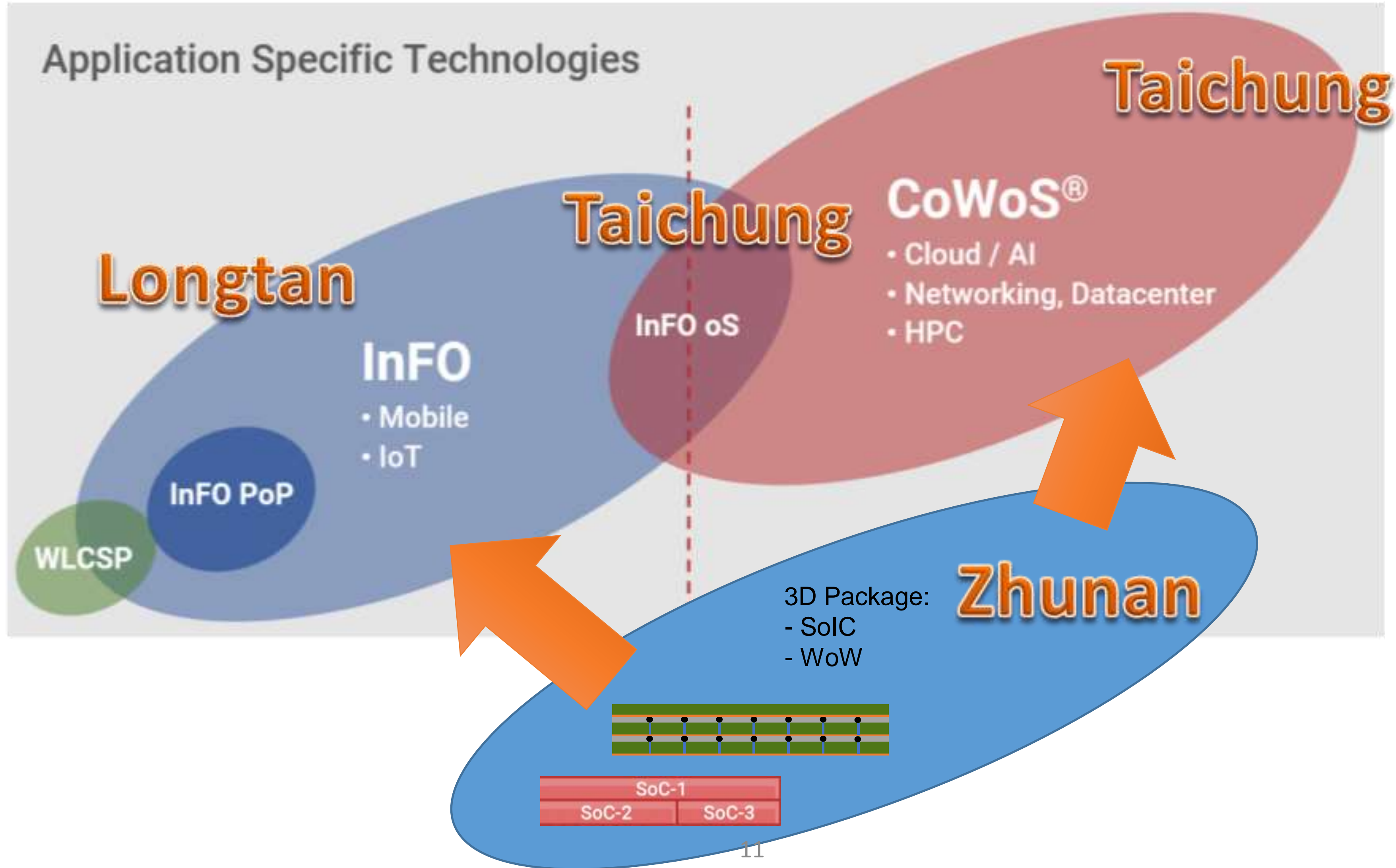
TSMC 3D Fabric



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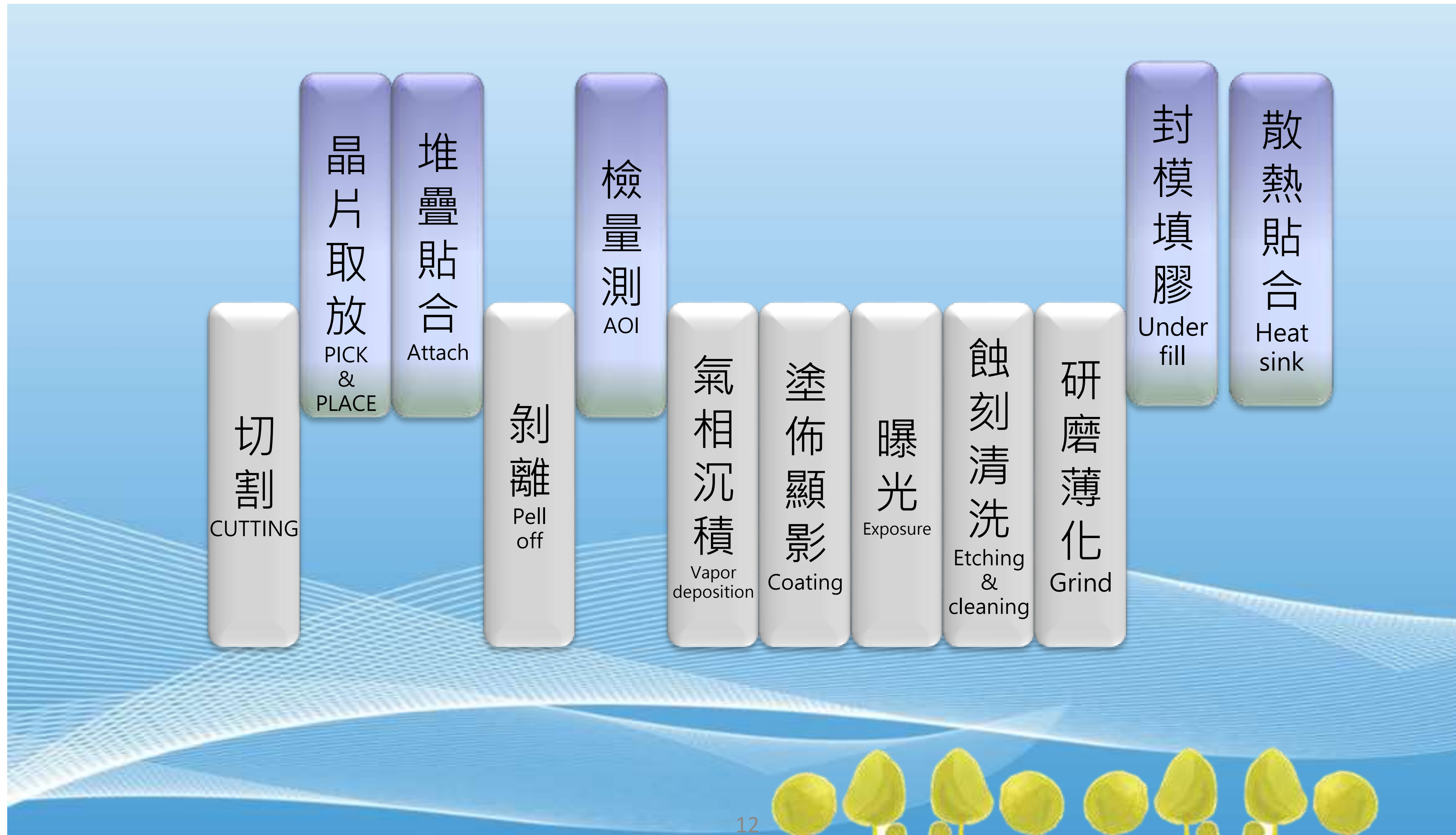
Allring in 3D Fabric Process



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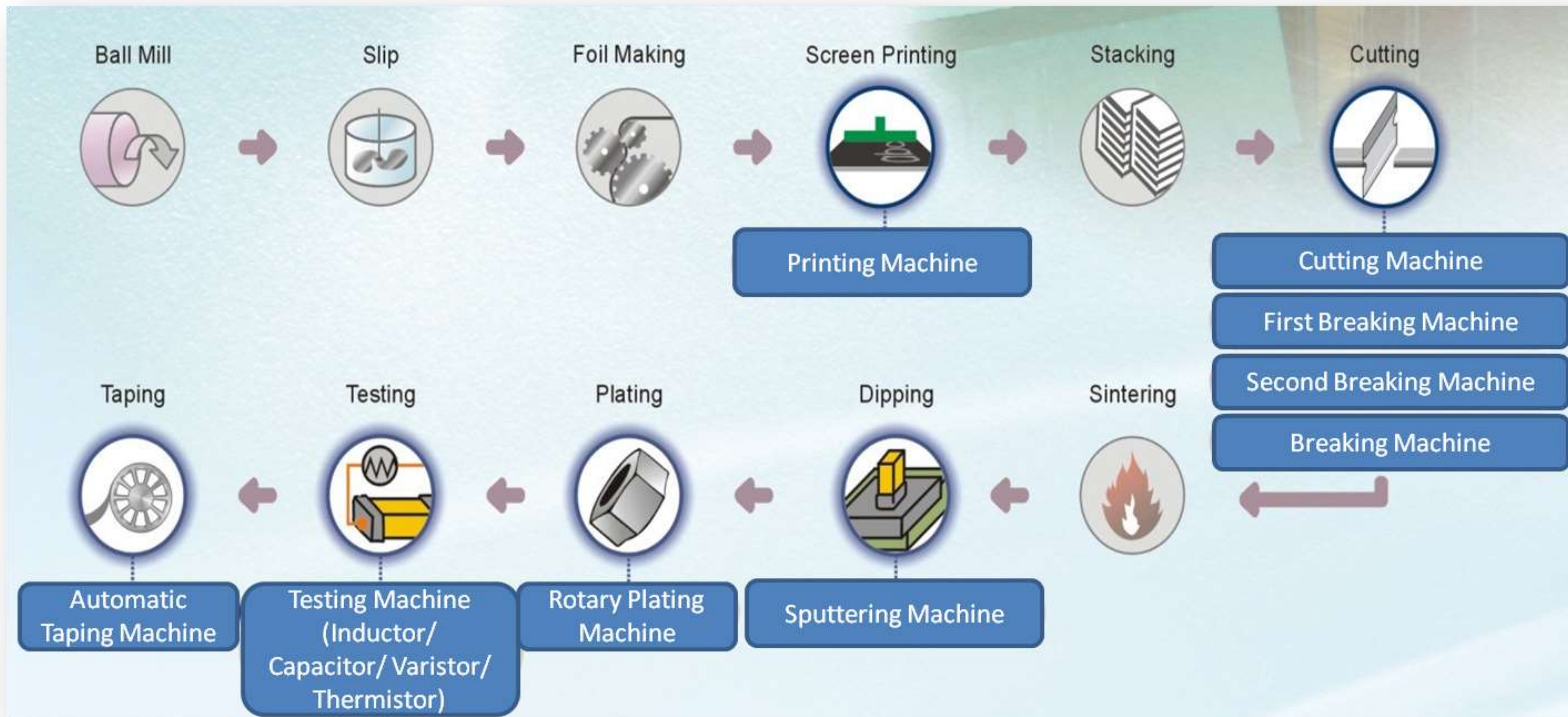
Passive Component Production Process



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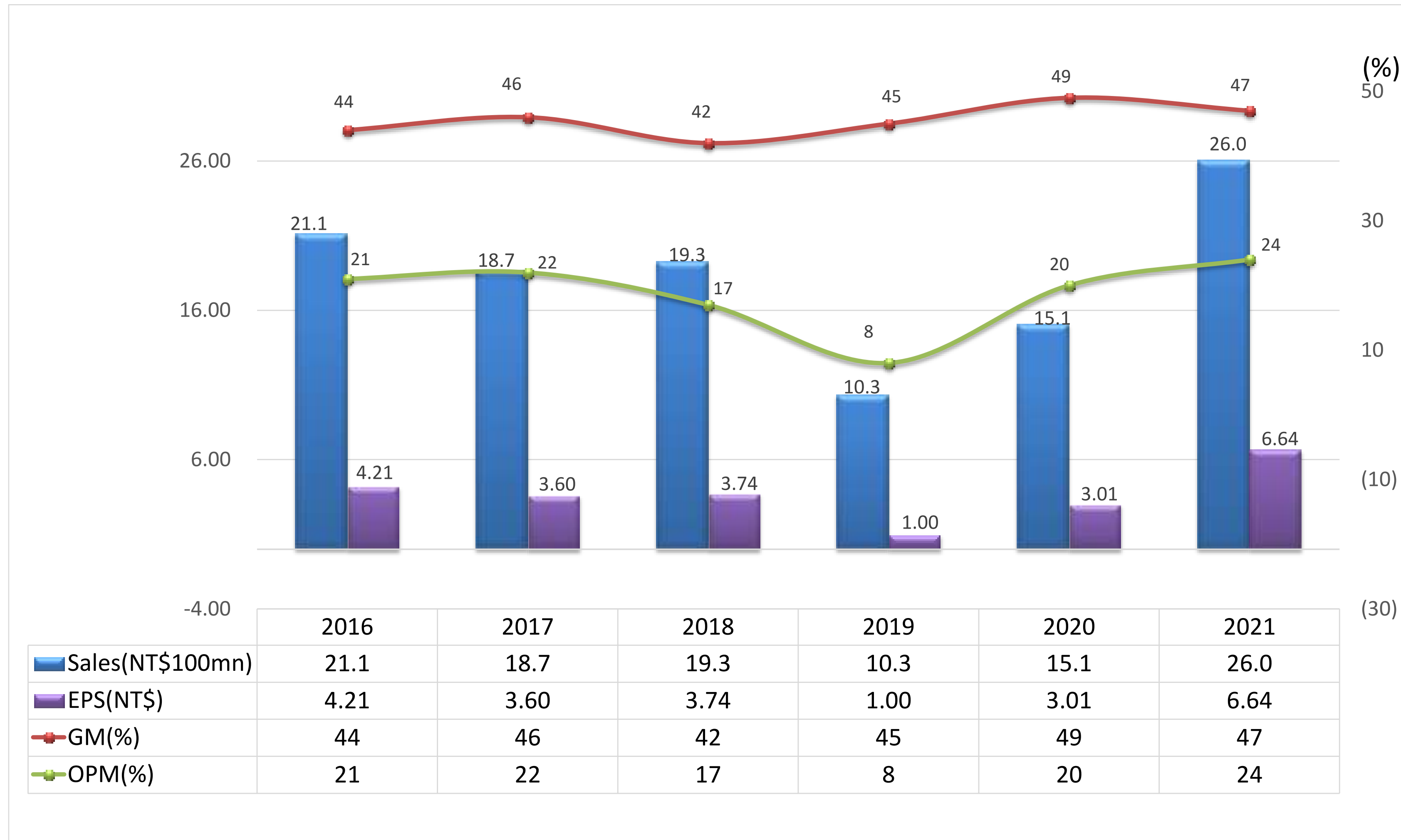
Revenue Breakdown

NT$100M

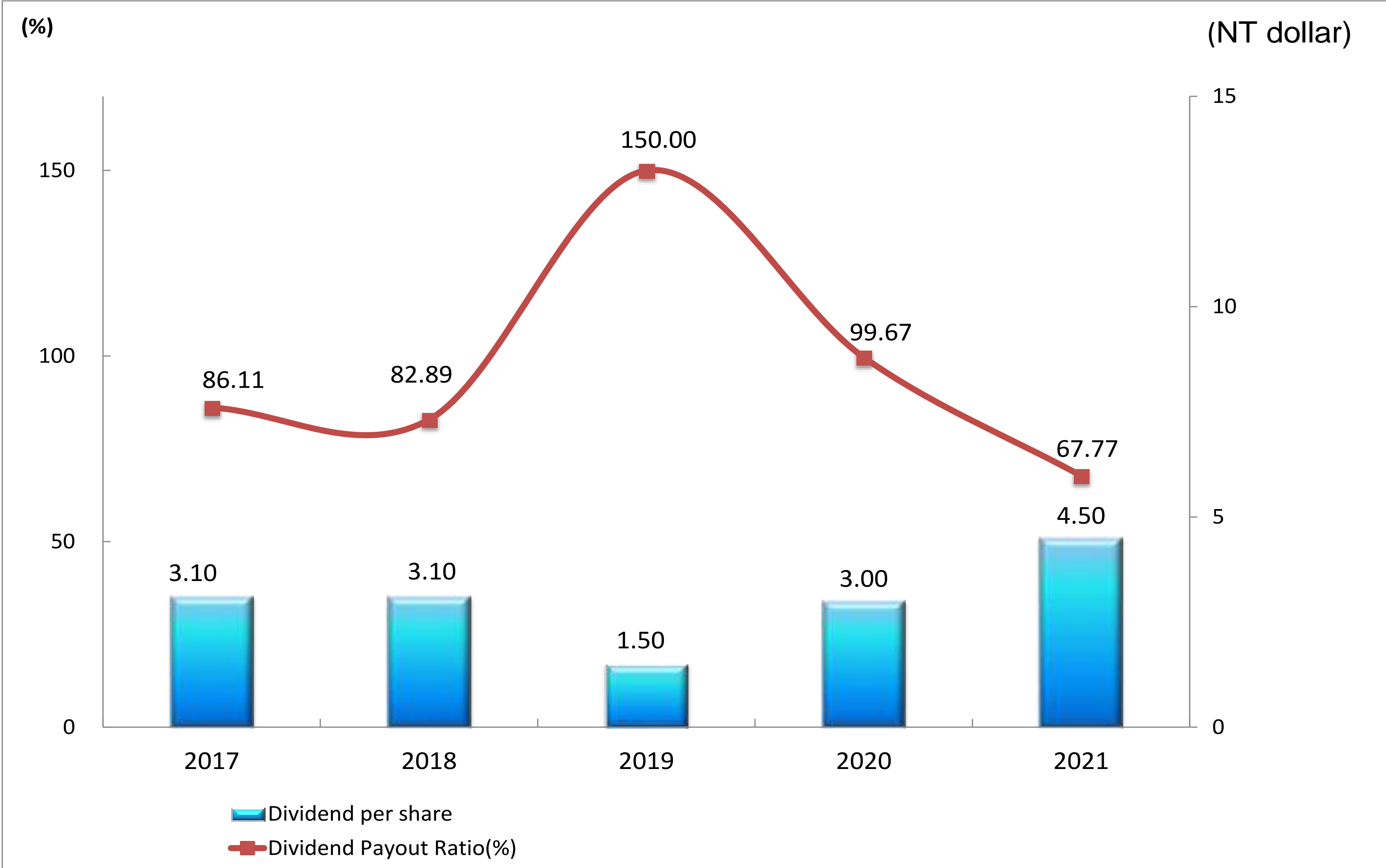
	2019		2020		2021	
SEMI	7.48	72%	9.28	62%	9.60	37%
PASSIVE	1.70	16%	4.14	27%	14.24	55%
OTHER	1.14	12%	1.64	11%	2.20	8%
TOTAL	10.32	100%	15.06	100%	26.04	100%

Financial Highlights



	2016	2017	2018	2019	2020	2021
Sales(NT$100mn)	21.1	18.7	19.3	10.3	15.1	26.0
EPS(NT$)	4.21	3.60	3.74	1.00	3.01	6.64
GM(%)	44	46	42	45	49	47
OPM(%)	21	22	17	8	20	24

Financial Highlights



Thank you!